

AMENDMENTS TO THE CLAIMS

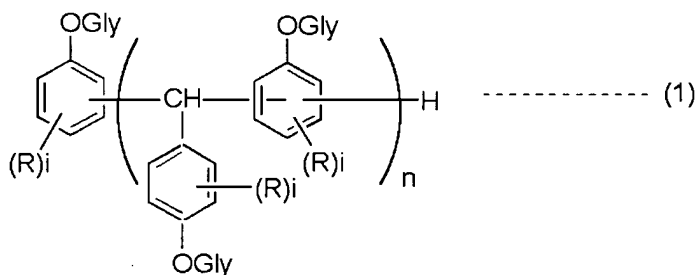
This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

1. (original): A resin film comprising (A) an epoxy resin having two or more glycidyl groups in a molecule, (B) an epoxy resin curing agent, (C) a thermoplastic resin, and (D) a filler, wherein the filler content in at least either one of the surface regions on the cross-section of the film is less than the filler concentration in the central region.

2. (original): A resin film according to claim 1, wherein two or more films are laminated.

3. (original): A resin film according to claim 1 or 2, wherein epoxy resin (A) having two or more glycidyl groups in a molecule is represented by following formula (1)



wherein, *n* represents an average repeating number of 1 to 10; a plurality of *R* each independently represents hydrogen atom, an alkyl group having 1-10 carbon atoms, an aralkyl group having 6-20 carbon atoms, an aromatic group having 6-20 carbon atoms, a cycloalkyl group having 5-7 carbon atoms or a hydrocarbon group having 6-20 carbon atoms containing a cycloalkyl group having 5-7 carbon atoms; *i* each independently represents an integer of 1-4; and Gly represents glycidyl group.

4. (currently amended): A resin film according to ~~any one of claims 1 to 31~~ or 2, wherein epoxy resin curing agent (B) is phenol novolak.

5. (currently amended): A resin film according to ~~any one of claims 1 to 31~~ or 2, wherein thermoplastic resin (C) is polyether sulfone.

6. (currently amended): A resin film according to ~~any one of claims 1 to 31~~ or 2, wherein filler (D) is silica.

7. (currently amended): A multilayer printed wiring board comprising an insulating layer obtained by curing the resin film according to ~~any one of claims 1 to 6~~ or 2.

8. (new): A resin film according to claim 3, wherein epoxy resin curing agent (B) is phenol novolak.

9. (new): A resin film according to claim 3, wherein thermoplastic resin (C) is polyether sulfone.

10. (new): A resin film according to claim 3, wherein filler (D) is silica.

11. (new): A multilayer printed wiring board comprising an insulating layer obtained by curing the resin film according to claim 3.

12. (new): A multilayer printed wiring board comprising an insulating layer obtained by curing the resin film according to claim 4.

13. (new): A multilayer printed wiring board comprising an insulating layer obtained by curing the resin film according to claim 5.

14. (new): A multilayer printed wiring board comprising an insulating layer obtained by curing the resin film according to claim 6.

15. (new): A multilayer printed wiring board comprising an insulating layer obtained by curing the resin film according to claim 8.

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Q79468
PRELIMINARY AMENDMENT

16. (new): A multilayer printed wiring board comprising an insulating layer obtained by curing the resin film according to claim 9.

17. (new): A multilayer printed wiring board comprising an insulating layer obtained by curing the resin film according to claim 10.